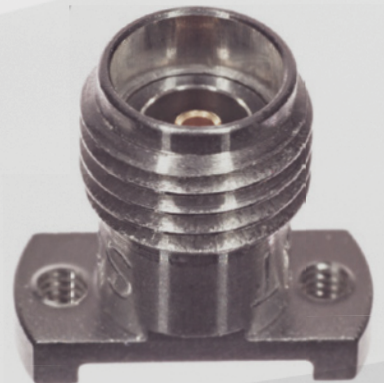




Vertical Launch Compression-Mount PCB Connectors

THE PERFORMANCE LEADER IN
MICROWAVE CONNECTORS



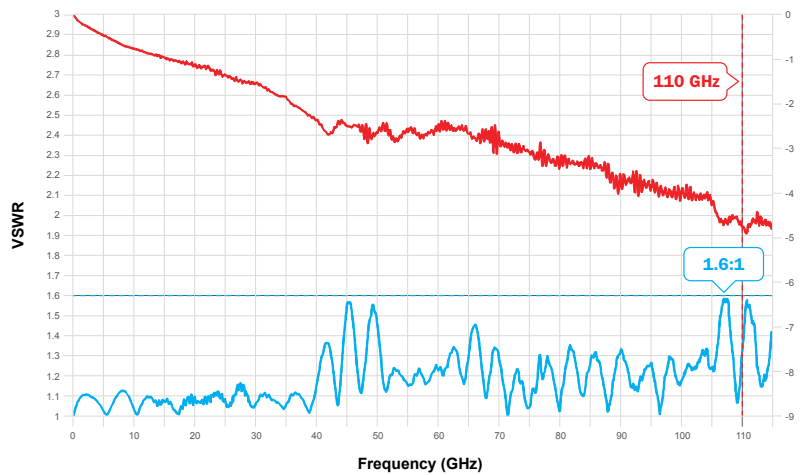
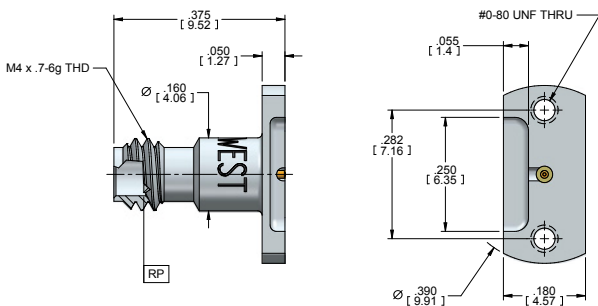
- Low VSWR
- Low Insertion Loss
- Low RF Leakage
- High Temperature
- Rugged & Durable
- Excellent Repeatability

TOP PERFORMANCE SOLDERLESS CONNECTORS

For microstrip or grounded coplanar waveguide (GCPW) designs, Southwest Microwave vertical launch connectors provide optimal signal integrity, are reusable and can be installed without soldering. Suitable for various board materials and thicknesses, the vertical launch connectors reduce footprint requirements without sacrificing performance, resulting in design and installation convenience.

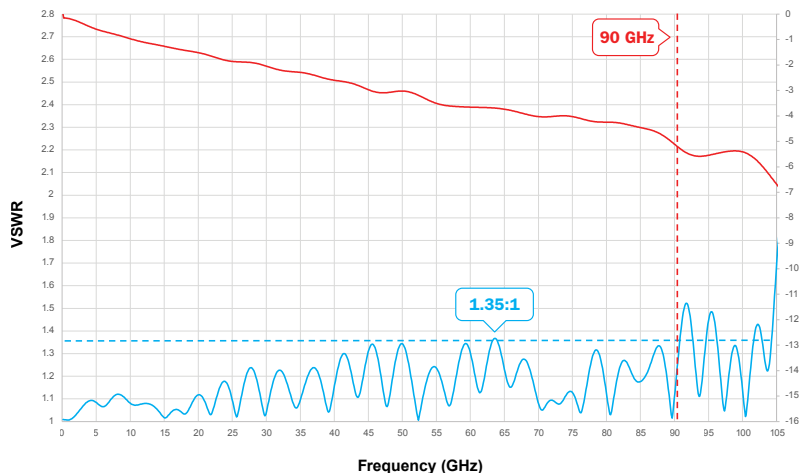
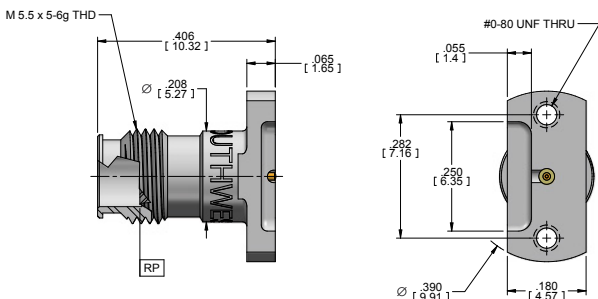
1.0 MM (W) DC TO 110 GHz (24359-001J)

VSWR of 1.16:1 max per connector across 70 to 105 GHz and a **VSWR of 1.26:1 max across the complete 110 GHz** bandwidth. Data represent two 1.0 mm connectors mounted on 5 mil R03003 test-board.



1.35 MM (E) DC TO 90 GHz (22359-001J)

VSWR of 1.25:1 max per connector across 90 GHz bandwidth. Data represent two 1.35 mm connectors mounted on 5 mil R03003 test-board.



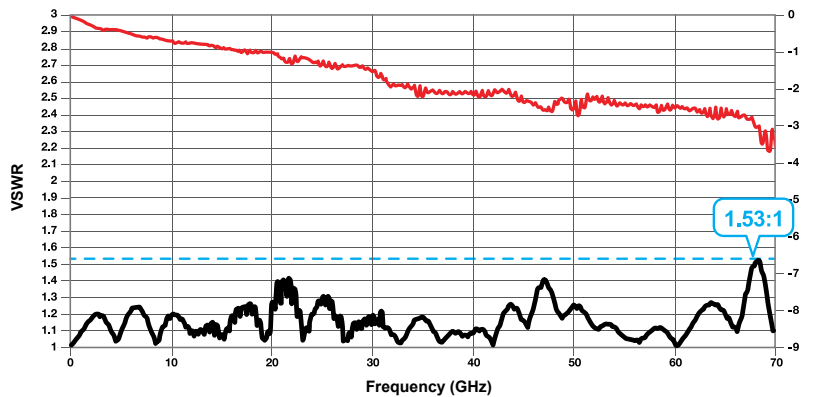
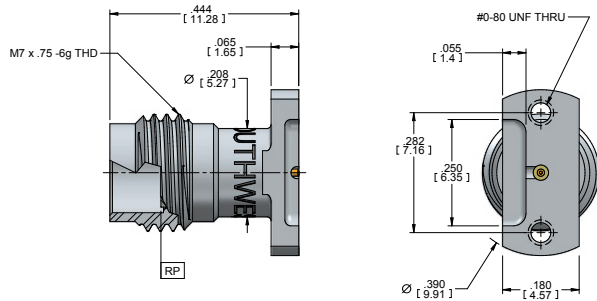
PROVEN INTERCONNECT SOLUTIONS

INDUSTRY-LEADING INNOVATION



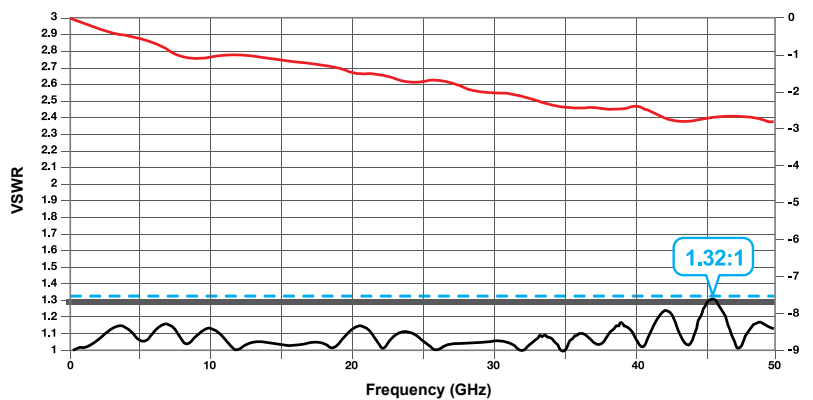
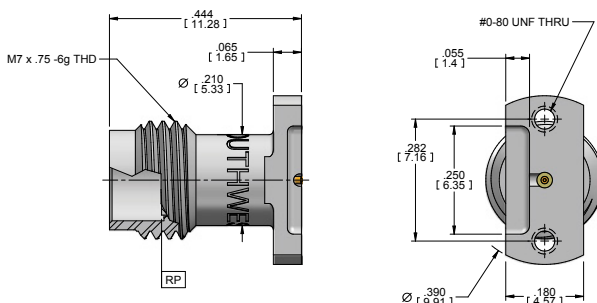
1.85 MM (V) DC TO 67 GHz (18359-001J)

VSWR of 1.25:1 max per connector across 67 GHz bandwidth. Data represent two 1.85 mm connectors mounted on 8 mil R04003 test-board.



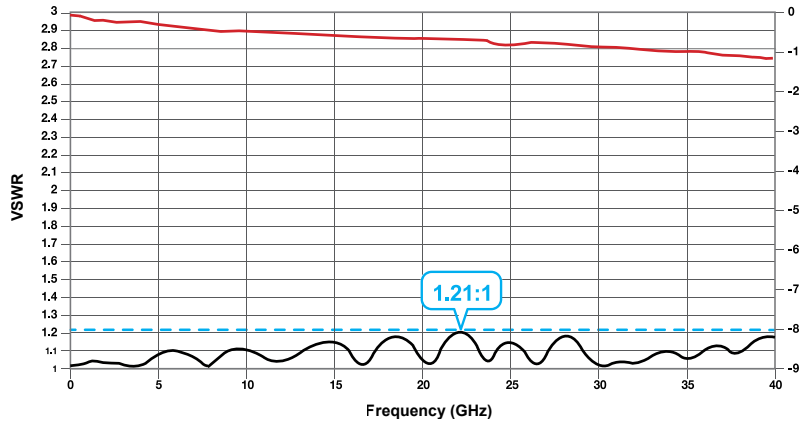
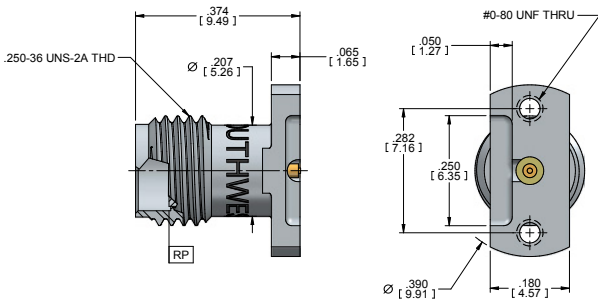
2.40 MM DC TO 50 GHz (14359-001J)

VSWR of 1.18:1 max across 50 GHz bandwidth. Data represent two 2.4 mm connectors mounted on 8 mil R04003 test board.



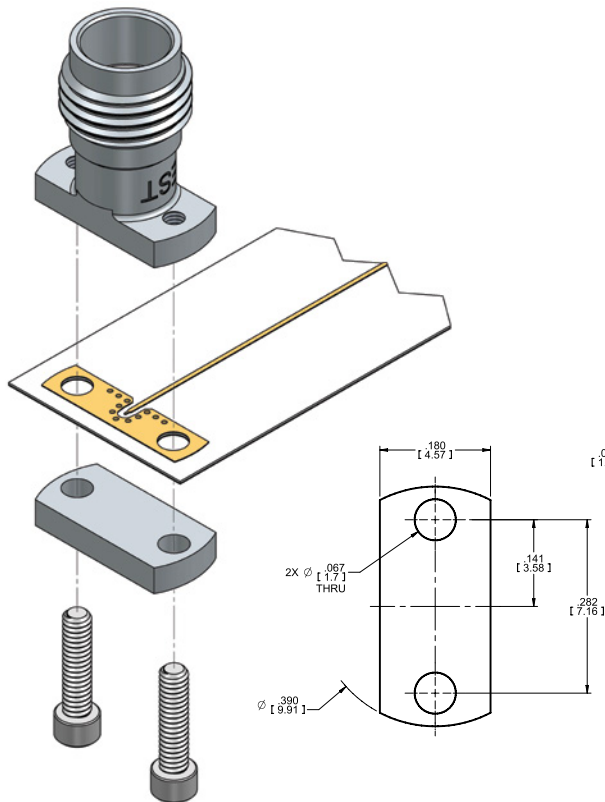
2.92 MM (K) DC TO 40 GHz (10359-002J)

VSWR of 1.095:1 max per connector across 40 GHz. Data represent two 2.92 mm connectors mounted on 8 mil RO4003 test-board.



ACCESSORY PLATE (290-127SF)

Vertical Launch Compression Mount for Thin Boards
APPLICATION DETAIL



DESIGN ASSISTANCE

- Printed circuit board layout and connector part number recommendation.
- 3D models for mechanical layout.
- HFSS models (version 18.0 or newer) for EM simulations upon request and availability.

SPECIFICATIONS

ENVIRONMENTAL

- Temperature: -55 to +165 °C

MATERIALS / CONSTRUCTION

- **Connector Housing:** CRES Alloy UNS S30300 per ASTM A582, Passivated per ASTM A967
- **Contact:** BeCu, UNS C17300 per ASTM B196, Au plated per MIL-G-45204 or ASTM B488
- **Center Contact Capture:** Ultem 1000 per ASTM D5205

CONNECTOR INTERFACE:

- 1.0 mm – Per IEEE-287
- 1.35 mm – Per IEEE-287
- 1.85 mm – Per IEEE-287
- 2.40 mm – Per MIL-STD-348, Figs. 324-1 and 324-2
- 2.92 mm – Per MIL-STD-348, Figs. 323-1 and 323-2